Open. Together.
Open Accelerator Module Project (OAM) is now the Open Accelerator Infrastructure Project (OAI)
Open Accelerator Infrastructure
Open Accelerator Infrastructure

- OAI overall spec
- Universal Base Board (UBB)
- Host Interface Board (HIB)
- Power Distribution Board (PDB)
- OAM tray
- Security, Control, Management
- Chassis mechanical and cooling
- Expansion beyond Chassis
Open Accelerator Infrastructure

- Open Accelerator Module (OAM) spec released
- Universal Baseboard (UBB) spec in development
- Inspur showing first UBB today
- Prototype samples today at the Summit
- Inspur announces developer systems support
Universal Baseboard (UBB)
Open Domain-Specific Architecture Project

Significant Performance Advantages
Open Domain-Specific Architecture Project

Chiplets offer costs savings & heterogeneous integration options

*AMD Data
ODSA Project Work Streams

PoC (Achronix/zGlue)

Interface/Standards (AveraSemi, Facebook)

Business, IP and Workflow (NXP, Kandou Bus)

- Develop Packaging + Socket, Dev Board
- Define Architectural Interface
- Provide PHY technology
Open Domain-Specific Architectures Project

• Chiplet Design Data Exchange being defined
• Bundle of Wires (BoW) interconnect paper released to WIKI
• BoW proof of concept milestone achieved today
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